

ABSTRACT

A high-impedance substrate including a first layer made of insulating material, having a lower face and an upper face, the substrate including conductor patterns mechanically linked to the substrate. Some of the conductor patterns mechanically linked to the substrate are associated with a magnetic tile. At least one electrical interconnection puts two points distinct from one another of a conductor pattern mechanically linked to the substrate in electrical contact, this conductor pattern having an assigned magnetic tile, passing above the magnetic tile associated with the conductor pattern mechanically linked to the substrate.